

L Number	Hits	Search Text	DB	Time stamp
-	216	(432/258).CCLS.	USPAT	2003/03/17 10:39
-	10	("hot plate" or (heat\$ ADJ3 plate)) and ((432/258).CCLS.)	USPAT	2003/03/17 10:37
-	134	(432/81).CCLS.	USPAT	2003/03/17 10:38
-	5	(wafer or substrate) and ((432/81).CCLS.)	USPAT	2003/03/17 10:39
-	415	(432/253).CCLS.	USPAT	2003/03/17 10:39
-	162	(wafer or substrate) and ((432/253).CCLS.)	USPAT	2003/03/17 10:59
-	182	(211/41.18).CCLS.	USPAT	2003/03/17 10:59
-	167	(wafer or substrate) and ((211/41.18).CCLS.)	USPAT	2003/03/17 11:24
-	377	(392/418).CCLS.	USPAT	2003/03/17 11:24
-	174	(wafer or substrate) and ((392/418).CCLS.)	USPAT	2003/03/17 11:50
-	2149	((118/724) or (118/725)).CCLS.	USPAT	2003/03/17 11:50
-	1694	(wafer or substrate) and (((118/724) or (118/725)).CCLS.)	USPAT	2003/03/17 12:26
-	284	((baking or heat\$) ADJ3 plate) and ((wafer or substrate) and ((118/724) or (118/725)).CCLS.))	USPAT	2003/03/17 12:37
-	58	recess and (((baking or heat\$) ADJ3 plate) and ((wafer or substrate) and (((118/724) or (118/725)).CCLS.)))	USPAT	2003/03/17 12:04
-	226	((baking or heat\$) ADJ3 plate) and ((wafer or substrate) and ((118/724) or (118/725)).CCLS.)) not (recess and (((baking or heat\$) ADJ3 plate) and ((wafer or substrate) and ((118/724) or (118/725)).CCLS.)))	USPAT	2003/03/17 12:26
-	98	(219/444.1).CCLS.	USPAT	2003/03/17 12:26
-	91	(wafer or substrate) and ((219/444.1).CCLS.)	USPAT	2003/03/17 12:36
-	46762	438/\$.ccls. and (wafer or substrate)	USPAT	2003/03/17 12:37
-	580	((baking or heat\$) ADJ3 plate) and (438/\$.ccls. and (wafer or substrate))	USPAT	2003/03/17 12:40
-	74	recess and (((baking or heat\$) ADJ3 plate) and (438/\$.ccls. and (wafer or substrate)))	USPAT	2003/03/17 12:40